X RAY FLUORESCENCE SPECTROMETER/FILM THICKNESS GAGE (PROFESSIONAL TYPE) CODE XRF-PT230



- Application fields: electroplating coating thickness analysis, inspection of electronic components such as connectors, fastener industry, automotive parts, hardware industry (household equipment and accessories, such as Cr/Ni/CuZn(ABS)), new energy industry (photovoltaic welding wire, etc.), thickness analysis of accessories, NI/Cu/Ni/FendB on rubidium iron boron magnets, metal cation detection in electroplating solution, etc.
- It can detect 90 types of coating elements and be used in the analysis of 77 types of elemental composition in geology, alloys, precious metals,
- Equipped with a micro-focus X-ray generator and an advanced light path conversion focusing system, the minimum measurable area is up to 0.03mm².
- It has non-destructive manual zoom detection technology, which can perform non-destructive testing on various shaped and irregular grooved parts from 0 to 30mm.
- Equipped with Si-Pin semiconductor detector, high resolution, fast testing speed, stable data, equipped with micro-light focusing technology, ranging spot diffusion less than 10%.
- The core EFP algorithm allows for the simultaneous analysis of 23 coating and 24 elements. It can quickly, accurately, and stably analyze multiple layers and multiple elements, including the same element in different layers.
- User-friendly closed software, automatically identifies faults, provides calibration and operation steps, and avoids misoperations.

STANDARD DELIVERY

Main unit	1pc
Computer	1pc
Printer	1рс
Accessory box	1pc
Twelve element plate	1pc
Standard plate	2pcs*

OPTIONAL DELIVERY

Electroplating solution measuring	XRF-PT230-MC
cup	

*Standard plate with the following ten specifications to choose from, based on demand, with two options selected

Sort	Standard plate	Dimension
Pure element	Cr	0.15µm
	Ni	5µm
	Zn	10µm
	Cu	8µm
	Ag	0.5µm
	Au	0.05µm
Substrate coating	Ni/Cu	2µm
	ZnNi/Fe	10µm
	ZnNi/Cu	5µm/0.7µm
	ZnNi/Cu	10µm/4µm

SPECIFICATION

Coating layer analysis	Elemental analysis range	Li (3)-U (92)	
	Detection limit	0.005µm	
	Analysis thickness	0.01-80µm (detection limit for different elements is different)	
	Repeatability	0.1µm (<1µm thin outer coating)	
	Stability	0.1µm (<1µm thin outer coating)	
Composition analysis	Elemental analysis range	S (16)-U (92)	
	Detection limit	2ppm	
	Content analysis range	2ppm~99%	
	Repeatability	0.1%	
	Stability	0.1%	
EFP alaorithm		standard configuration	
Measuring time		5~300s	
Detector		Si-Pin semiconductor detector	
X-ray source		micro-focusing X-ray tube	
Collimator		Standard: Φ0.3mm (Φ0.5mm, Φ0.3mm, Φ0.2mm, 0.1×0.3mm) four collimators optional, customized acceptable	
Spot diffusivity		<10%	
Camera		1/2.7" color CCD, zoom function	
Measure distance		zoom lens 0~30mm	
Focus method		high-sensitivity lens, manual focus	
Enlargement factor		optical magnification 38~46X, digital magnification 40~200X	
Max sample height		210mm	
XY stage		manual high-precision XY stage	
Available moving range		50mm×50mm	
Operating environment		15~30°C, <70%RH	
Power		AC220V, 50Hz, 95W	
Dimension (L×W×H)		545×380×435mm	
Weight		48kg	